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PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Michael Bauer	10/10/2006
Ludwig Heitzer	10/10/2006
Eric Kuerzel	10/10/2006
Peter Strobel	10/10/2006

RECEIVING PARTY DATA

Name:	Infineon Technologies AG	
Street Address:	StMartin-Str. 53	
City:	Munich	
State/Country:	GERMANY	
Postal Code:	81669	

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	11543983	

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	3002.0059C	
NAME OF SUBMITTER:	Patrick J. Finnan	

PATENT REEL: 018578 FRAME: 0235

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Total Attachments: 2 source=ExecutedAssign#page1.tif source=ExecutedAssign#page2.tif

PATENT REEL: 018578 FRAME: 0236

REF NO. FIN 781 O.C. REF NO. 3002.0059C

ASSIGNMENT

For good and valuable consideration, WE, Michael Bauer, a citizen of Germany, residing at Dachgred 31, 93152 Nittendorf, Germany; Ludwig Heitzer, a citizen of Germany, residing at Augustenstrasse 15, 93049 Regensburg, Germany; Eric Kuerzel, a citizen of Germany, residing at Schottenstrasse 7, 93047 Regensburg, Germany; and Peter Strobel, a citizen of Germany, residing at Weisgerbergraben 4, 93047 Regensburg, Germany, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to Infineon Technologies AG, a corporation organized and existing under the laws of Germany, having its principal place of business at St.-Martin-Str. 53, 81669 Munich, Germany, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

filed on	US. Scrial No,
entitled:	Semiconductor Device with Semiconductor Chip and Adhesive Film and Method for Producing the Same

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignce may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignce, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignce, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements an the history thereof; and generally do everything possible which said Assignce, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignce, its successors, assigns and legal representatives; and

Covenant with said Assignee, it successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE:	Michael Bauer Michael Bauer	DATE:	10.10.2006
SIGNATURE:	Ludwig Heitzer	DATE:	10.10.06

REF NO. FIN 781 O.C. REF NO. 3002.0059C

SIGNATURE:

SIGNATURE:

Eric Kuerzel

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PATENT

RECORDED: 12/04/2006

REEL: 018578 FRAME: 0238